



Product Change Notification

Date Issued :	February 06, 2026	PCN Number :	517804
Reason for Change :	Change Supplier		
Description of Change :	This notification is to inform you about change of supplier impacting the part(s) attached as per list, No changes will be made to product as part of this change		
Assessment of Change :	Reliability Test Report/s		
Planned Implementation Date :	August 06, 2026		
Customer Sample Availability Date:	March 15, 2026		
Last date to request Samples by Customer : March 30, 2026			
Please note if Samples are not requested as per Customer Samples Request date, it may take additional 4-6 weeks to arrange Samples.			
Traceability Code Markings / Date :	No special marking on the product or packaging		

Before Picture

Overview

Semiconductor ADI is going to change below for standard part AD2428WCCSZ-RL with formal announcement in the market, to ensure the smoothly supplier chain.

- 1, Bond wire change from Gold to Copper.
- 2, The raw material of Mold compound type changed from Sumitomo G770 to Sumitomo G700LA.
- 3, Die attach material(adhesive) change from Ablestik 3230 to Hitachi EN4900GC.
- 4, Bond wire thickness change from 1.0 mil to 0.8 mil.

- **Product Impact**
 - No impact to fit, form, function.

- **Part Number Impact**
 - See attached impacted parts list

- Qualification Reports and samples available upon request.

- PCN will be implemented once all required qualification/ validation has been completed and all necessary approvals have been obtained.

You may address inquiries regarding this PCN by clicking on the below link
mailto:pcn_coordinator@molex.com?subject=PCN_Notification:517804
 or contact your Local Sales Engineer.

Note: While responding, please retain " PCN Notification : **PCN Notification: 517804** " in the e-mail Subject line for faster response.

Molex, LLC

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